1. Record Nr. UNINA9910460003603321

Titolo	11th international congress molded interconnect devices : scientific proceedings : selected, peer reviewed papers from the 11th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany / / edited by Jorg Franke [and three others]
Pubbl/distr/stampa	Pfaffikon, Switzerland : , : TTP, , 2014 Enfield, New Hampshire : , : Trans Tech Publications Ltd, , [date of distribution not identified] ©2014
ISBN	3-03826-636-1
Descrizione fisica	1 online resource (119 p.)
Collana	Advanced Materials Research, , 1662-8985 ; ; Volume 1038
Disciplina	621.367
Soggetti	Molded interconnect devices Three-dimensional display systems Electronic books.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing TechnologiesPrinting of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and

Manufacturing; Characterization of Electromagnetic Properties of MID Materials for High Frequency Applications up to 67 GHz
Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray MethodExperimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography; MID Fabricated by Ultrasonic Processing; Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation; Chapter 4: Manufacturing Processes; Study of MID Technologies for Automotive Lighting and Light Signaling Devices; Chapter 5: Assembly Technologies and Inspection
Design and Solder Process Optimization in MID Technology for High Power ApplicationsChapter 6: Quality and Reliability; Hot Pin Pull Method - New Test Procedure for the Adhesion Measurement for 3D-MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers are grouped as follows: Chapter 1: Development and Prototyping, Chapter 2: Printing Technologies, Chapter 3: Materials and Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5: Assembly Technologies and Inspection, Chapter 6: Quality and Reliability.

2. Record Nr. UNISA996213834703316

Titolo	Tests and Proofs [[electronic resource]] : 8th International Conference, TAP 2014, Held as Part of STAF 2014, York, UK, July 24-25, 2014, Proceedings / / edited by Martina Seidl, Nikolai Tillmann
Pubbl/distr/stampa	Cham : , : Springer International Publishing : , : Imprint : Springer, , 2014
ISBN	3-319-09099-2
Edizione	[1st ed. 2014.]
Descrizione fisica	1 online resource (XII, 214 p. 76 illus.)
Collana	Programming and Software Engineering ; ; 8570
Disciplina	004
Soggetti	Software engineering Computer programming Computer logic Mathematical logic Programming languages (Electronic computers) Computer simulation Software Engineering Programming Techniques Logics and Meanings of Programs Mathematical Logic and Formal Languages Programming Languages, Compilers, Interpreters Simulation and Modeling
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Bibliographic Level Mode of Issuance: Monograph
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Model-Based Mutation Testing of an Industrial Measurement Device -- Computing with an SMT Solver -- An Abstraction Technique for Testing Decomposable Systems by Model Checking -- An All-in-One Toolkit for Automated White-Box Testing -- Behaviour Driven Development for Tests and Verification -- Quality Assurance in MBE Back and Forth -- Visualizing Unbounded Symbolic Execution -- Film stripping and Unrolling: A Comparison of Verification Approaches for UML and OCL Behavioral Models -- Generating Classified Parallel Unit Tests -- JTACO: Test Execution for Faster Bounded Verification -- Explicit

	Assumptions - A Prenup for Marrying Static and Dynamic Program Verification -- A Case Study on Verification of a Cloud Hypervisor by Proof and Structural Testing -- Runtime Assertion Checking and Its Combinations with Static and Dynamic Analyses: Tutorial Synopsis -- Generating Test Data from a UML Activity Using the AMPL Interface for Constraint Solvers -- Lightweight State Capturing for Automated Testing of Multithreaded Programs -- How Test Generation Helps Software Specification and Deductive Verification in Frama-C.
Sommario/riassunto	This book constitutes the refereed proceedings of the 8th International Conference on Tests and Proofs, TAP 2014, held in York, UK, in July 2014, as part of the STAF 2014 Federated Conferences. The 10 revised full papers and 4 short papers presented together with two tutorial descriptions were carefully reviewed and selected from 27 submissions. The papers cover topics in the following four research areas: test generation, bridging semantic gaps, integrated development processes and bounded verification.